

SUBSTRATE PROCESSING METHOD AND SUBSTRATE PROCESSING APPARATUS

ABSTRACT OF THE DISCLOSURE

A substrate processing method includes a processing liquid
5 supplying step of supplying a processing liquid to a patterned
surface of a substrate having the patterned surface with
projections and recesses, a processing film forming step of
solidifying or curing the processing liquid supplied to the
patterned surface to form, so as to follow the projections and
10 the recesses of the patterned surface, a processing film which
holds a removal object present on the patterned surface and
a removing step of supplying a peeling liquid to the patterned
surface to peel the processing film from the patterned surface
together with the removal object, thereby removing the
15 processing film from the substrate, while such a state is kept
that the removal object is held by the processing film.

FIG. 7C